

SEMICONDUCTOR DEVICE PACKAGE AND METHOD OF MAKING THE SAME

ABSTRACT

A semiconductor device package and a method of making the same are provided. The semiconductor device includes a package substrate, a layer of conductive material, a group of channels, and a chip. The package substrate has a top layer. The top layer has a group of conductive vias formed therethrough. The conductive material layer is formed on the top layer of the package substrate. The group of channels are formed in the conductive material layer about at least some of the vias to define a group of contact pads on the vias. The chip is electrically coupled to the package substrate through the contact pads.